

# SOT917-5

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 4 mm x 4 mm 0.85 mm body

20 April 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN
<b>Package type industry code</b>	HVQFN20
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	3-4-2017
<b>Manufacturer package code</b>	SOT917

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	-	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	



HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 4 mm x 4 mm  
0.85 mm body

## 2. Package outline

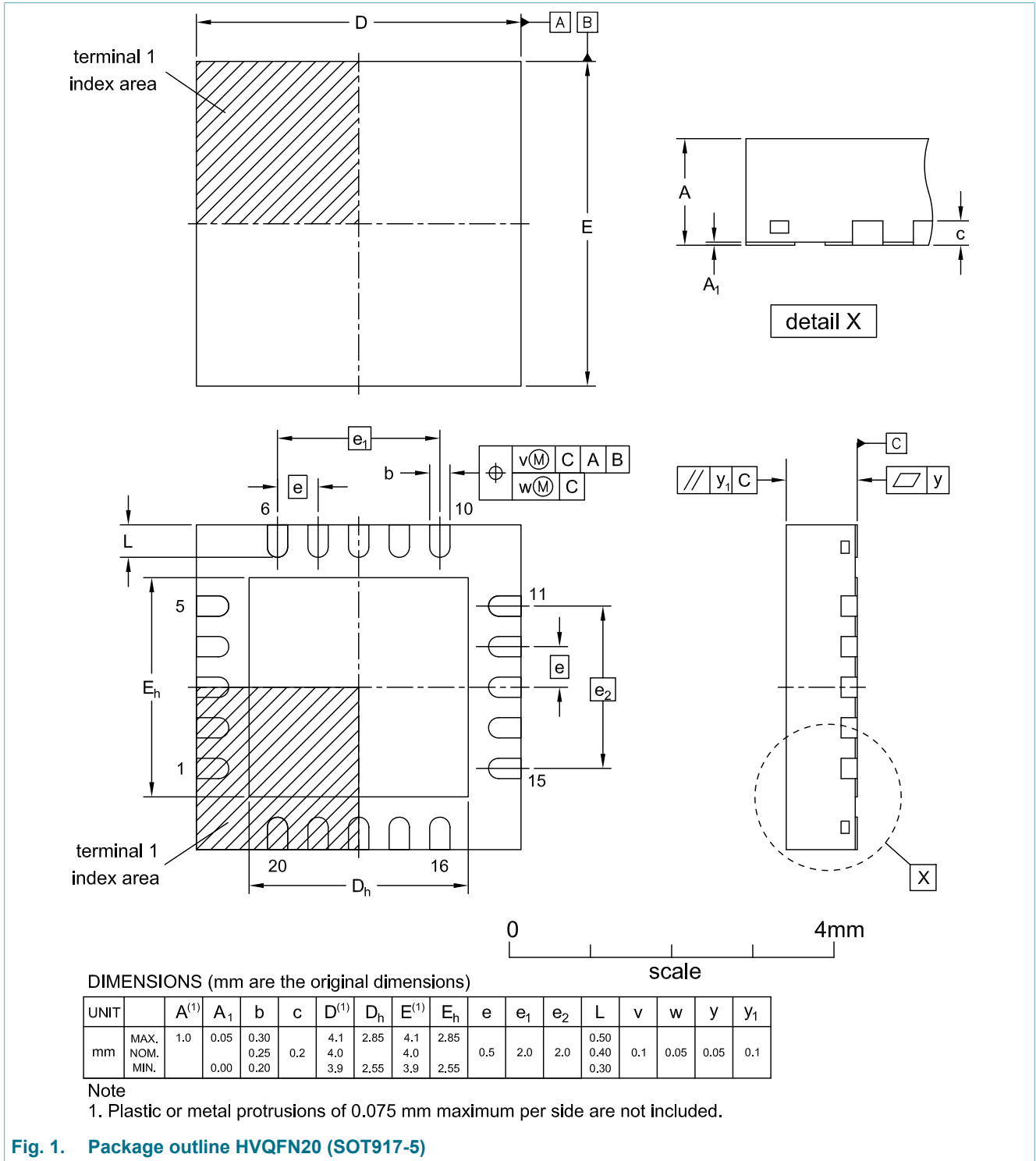


Fig. 1. Package outline HVQFN20 (SOT917-5)

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 4 mm x 4 mm  
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### 3. Soldering

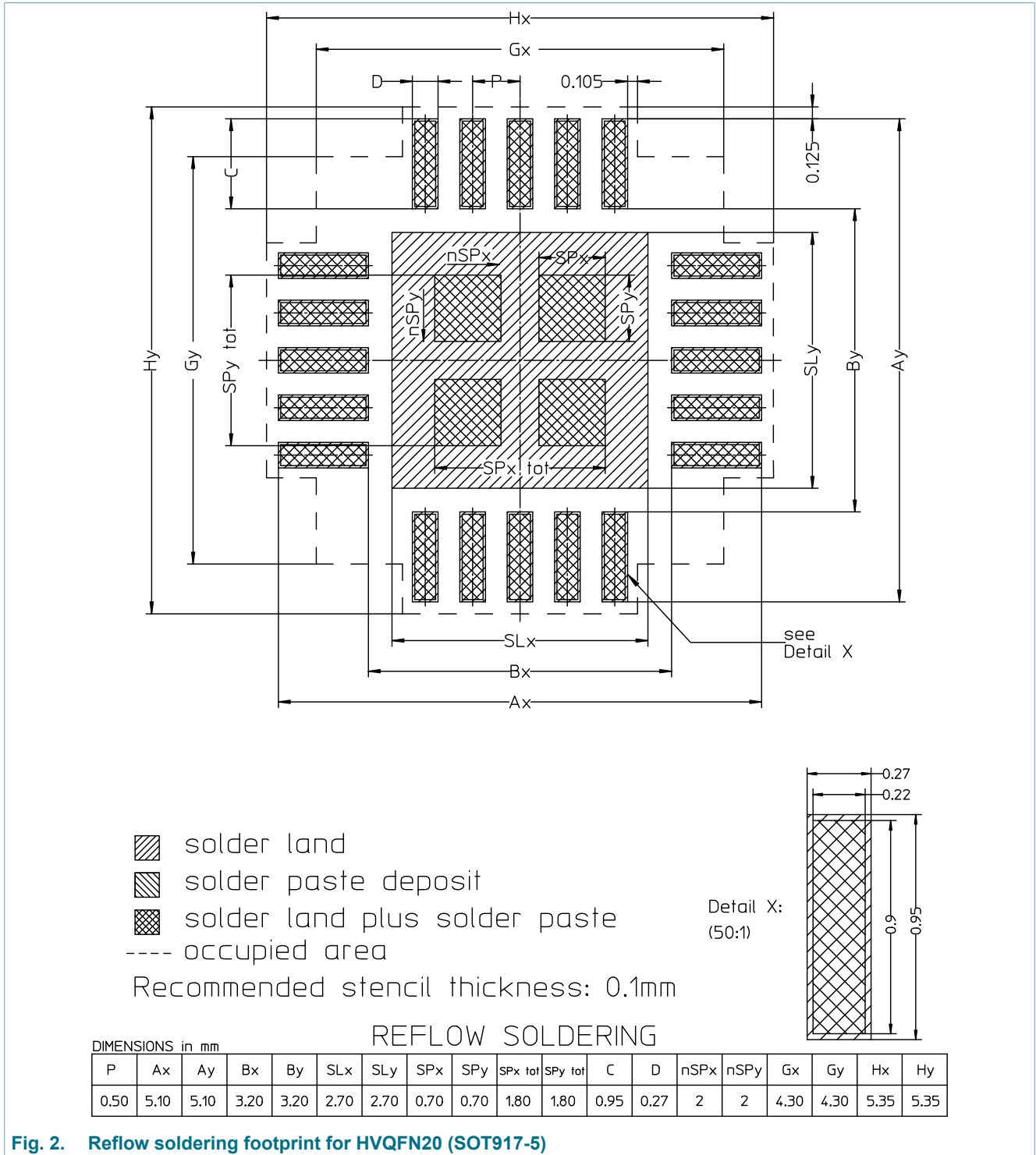


Fig. 2. Reflow soldering footprint for HVQFN20 (SOT917-5)

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## 4. Legal information

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Date of release: 20 April 2017

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